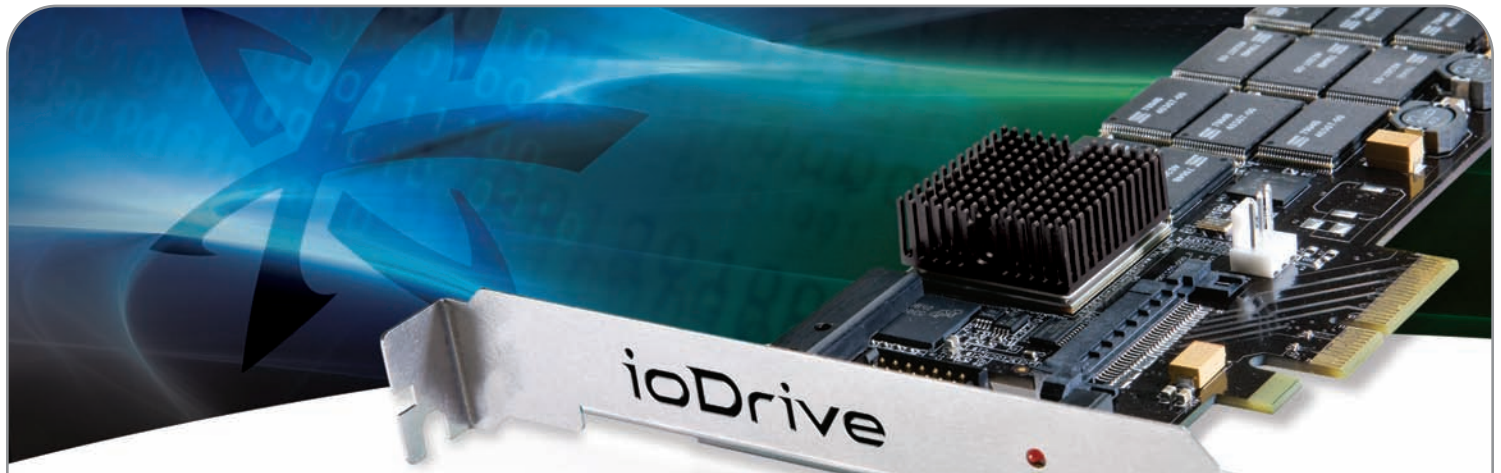


A 3D rendering of a glowing, light-blue path that curves through a field of grey, rectangular blocks. The path is illuminated from above, creating a bright, glowing effect. The blocks are scattered across the ground, some stacked and some lying flat. The overall scene is set against a dark, textured background.

ioDrive

## Breaking the Performance Barrier

The ioDrive shatters the performance barriers between processing and storage. Its innovative new architecture lets you deploy high-performance storage directly on the system bus, right next to your CPU, giving any server the performance of a multi-rack SAN. | [www.fusionio.com](http://www.fusionio.com)



- > Less than 50  $\mu$ s latency
- > Easily RAID multiple ioDrives together
- > Managed like simple block storage

ioDrive Capacity	80GB	160GB	320GB
NAND Type	Single Level Cell (SLC)	Single Level Cell (SLC)	Multi Level Cell (MLC)
Write Bandwidth	500 MB/s (32K packet size)	670 MB/s (32K packet size)	490 MB/s (64K packet size)
Read Bandwidth	750 MB/s (32K packet size)	750 MB/s (32K packet size)	700 MB/s (64K packet size)
IOPS*	119,790 (4k read packet size) 89,549 (75/25 r/w mix 4k packet size)	116,046 (4k read packet size) 93,199 (75/25 r/w mix 4k packet size)	71,256 (4k read packet size) 67,659 (75/25 r/w mix 4k packet size)
Access Latency	50 $\mu$ s Read	50 $\mu$ s Read	80 $\mu$ s Read
Bus Interface	PCI-Express x4	PCI-Express x4	PCI-Express x4
Weight	Less than 2 ounces	Less than 2 ounces	Less than 2 ounces
Operating Systems	Microsoft Windows**, Solaris 10***, RHEL 4 & 5; SLES 10 & 11	Microsoft Windows**, Solaris 10***, RHEL 4 & 5; SLES 10 & 11	Microsoft Windows**, Solaris 10***, RHEL 4 & 5; SLES 10 & 11
Wear Leveling and Sophisticated ECC (@ 5-TB write-erase / day)	24yrs	48yrs	16yrs

\* Performance achieved using multiprocessor enterprise server \*\* 64-Bit Windows XP, Vista, Server 2003 & 2008 \*\*\* Solaris support available in Q2 of 2009

### STANDARDS

Form Factor	Low profile PCI Express x4 slot (spec 1.1)
Connectivity	PCI Express x4 (electromechanical spec 1.1)
Power	PCI Express x4 (power spec 1.1)

### AGENCY

US / Canada	FCC Part 15, ICES-003, Class A
Europe	2004/108/EC EMC Directive CE Mark;
Japan	VCCI, Class A
Taiwan	BSMI, Class A
New Zealand /Australia	AS/NZS 3548 Class A
RoHS	R5 (Directive 2002/95/EC)

### ENVIRONMENTAL SPECIFICATIONS

		Min	Max
Temperature (°C)*	Operational	0	55
	Non-operational	- 40	70
Air Flow (LFM)		300	
Humidity (%)	Non-condensing	5	95
Altitude (ft)	Operational		10,000
	Non-operational		30,000

\* Temperature derated 1 C per 1000 ft elevation above sea level

### SAFETY

US / Canada	UL60950, CSA C22.2 No.60950-1-03
Europe	TUV EN60950-1:2001; 3N50825-1:

100% Assembled in the U.S.A.

